

EDHPC 2023

Redundant imaging payload data processing system based on a heterogeneous MPSoC

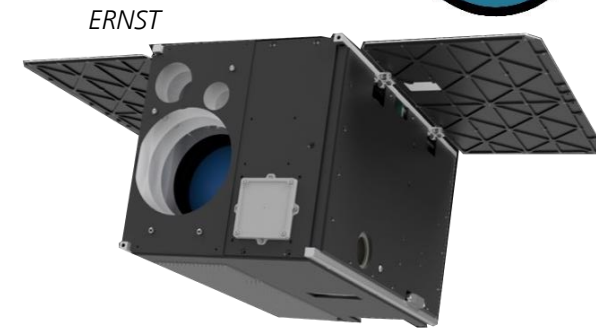
Clemens Horch, Daniel Garbe, Konstantin Schäfer

EMI Data Processing Unit Heritage

Mission	Launch	Software	FPGA	Hardware
Kent Ridge 1 and Kent Ridge 1B earth-observation microsatellite	12/2015	✓		
LisR external ISS-payload with TIR imager	02/2022	✓	✓	✓
NExSat 1 earth-observation microsatellite	tbd	✓	✓	
undisclosed earth-observation microsatellite	tbd	✓	✓	
undisclosed earth-observation microsatellite	06/2023	✓	✓	
ERNST 12U nanosatellite with MWIR-imaging	06/2024	✓	✓	✓
HiVE earth-observation microsatellite constellation, TIR and VNIR	06/2024	✓	✓	✓

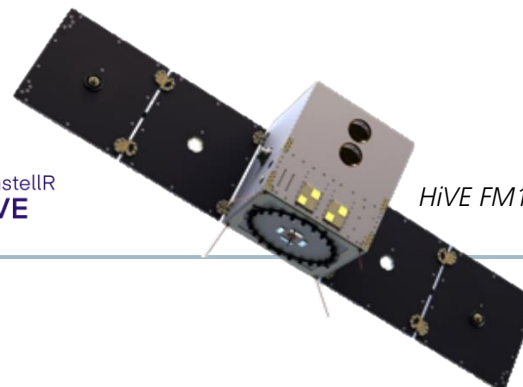
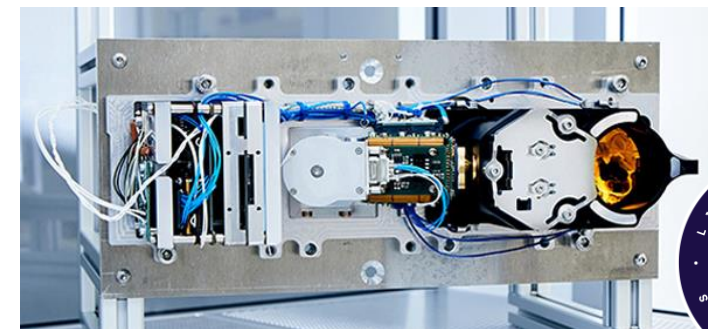


Kent Ridge 1



ERNST

LisR



HiVE FM1

EMI Data Processing Unit

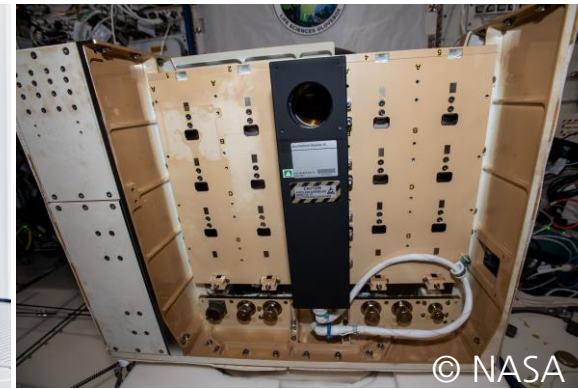
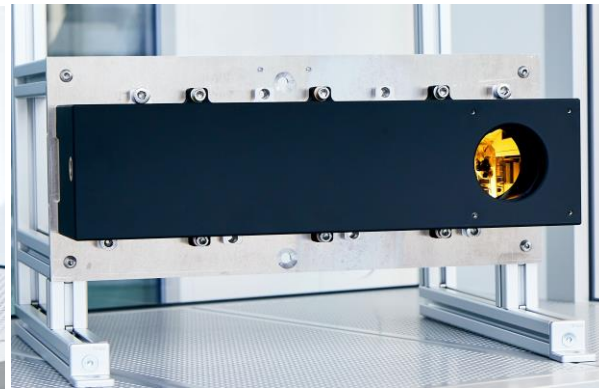
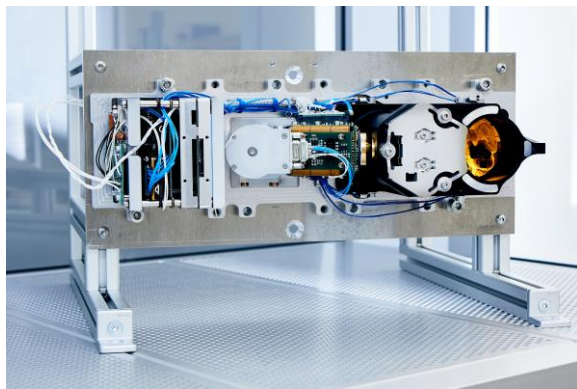
Six months in Orbit with LisR

- Long wave Infrared demonStratoR
- EXIST-Project of constellr
- Cryo-cooled thermal sensor
- NanoRacks External Platform on ISS
- Swath Width 25 km, GSD 80 m
- 20 weeks of recorded uptime
- Six successful software updates
- 9.3+ million frames captured
- ~500 million km² land surface captured

Fraunhofer
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River Rhine near Breisach April 2022



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EMI Data Processing Unit

Baseline Design (LisR mission)

Default Configuration

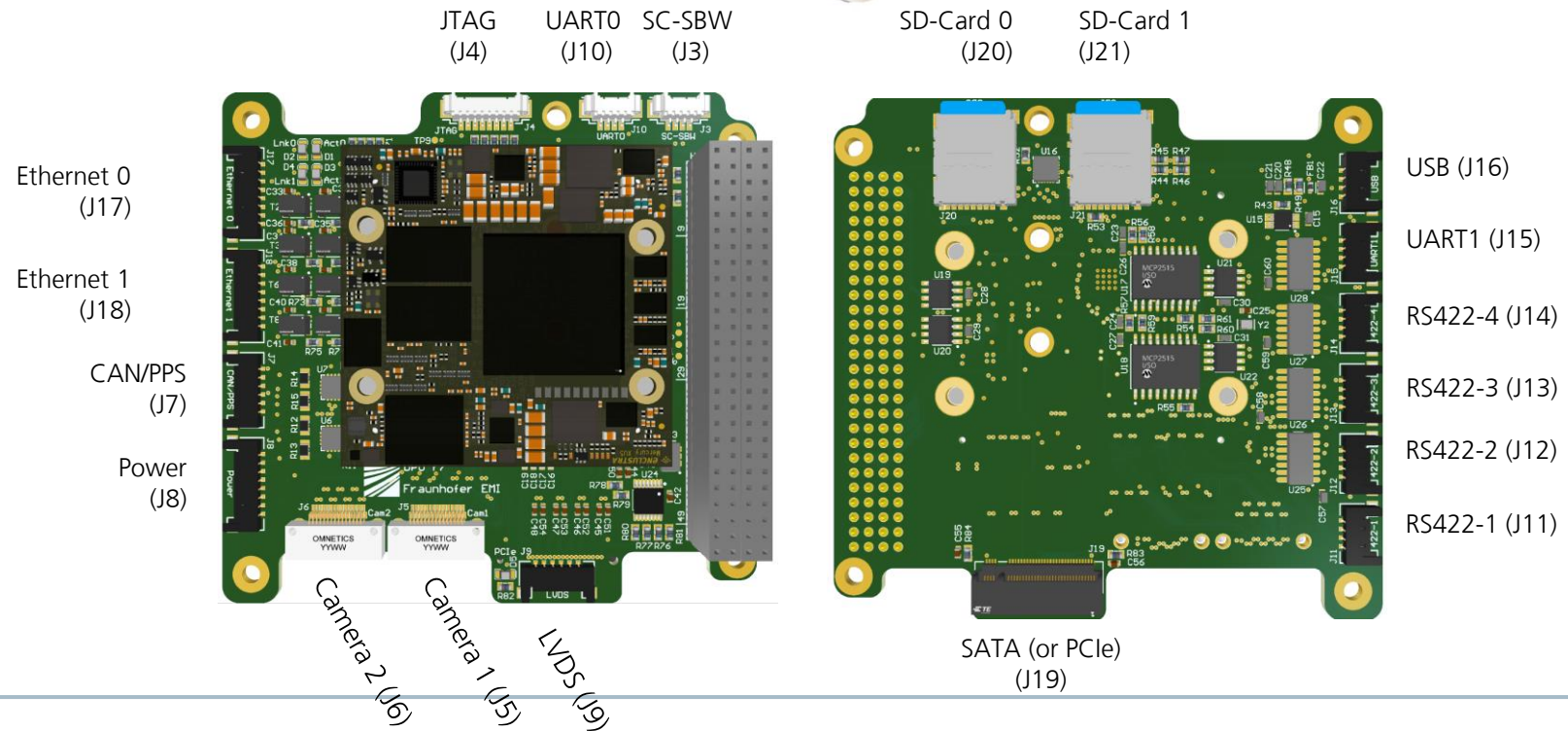
- CubeSat Mounting Standard (PC/104)
- Size: ~ 100 x 100 x 25 mm²
- Weight: ~ 0.4 kg
- Average Power: ~8W

Interfaces

- RS422 (4x)
- Ethernet (2x)
- USB
- CAN (2x)
- LVDS
- Camera Link

Storage

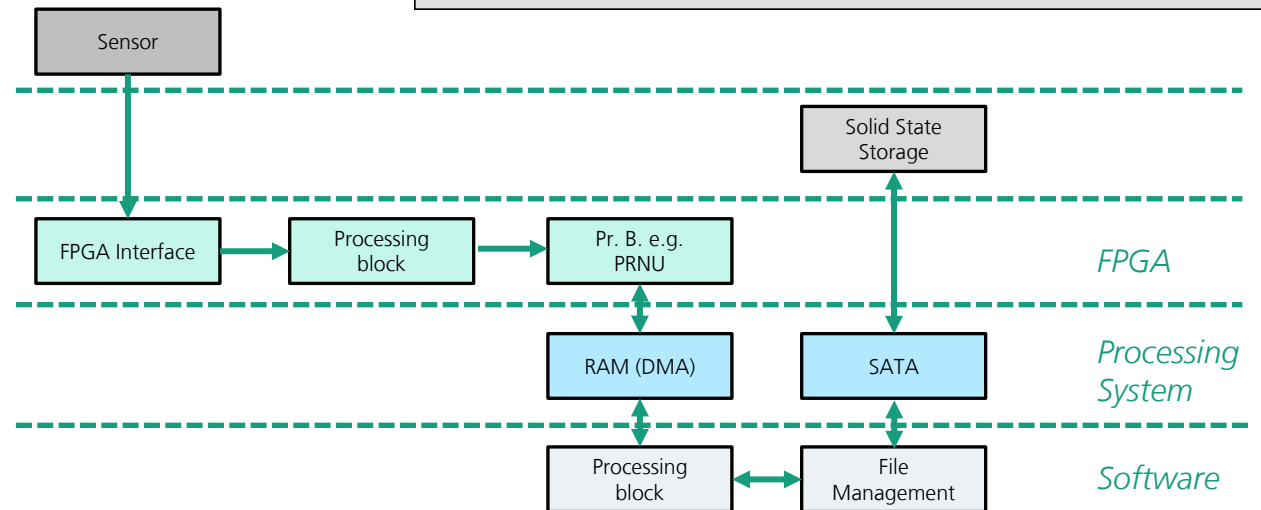
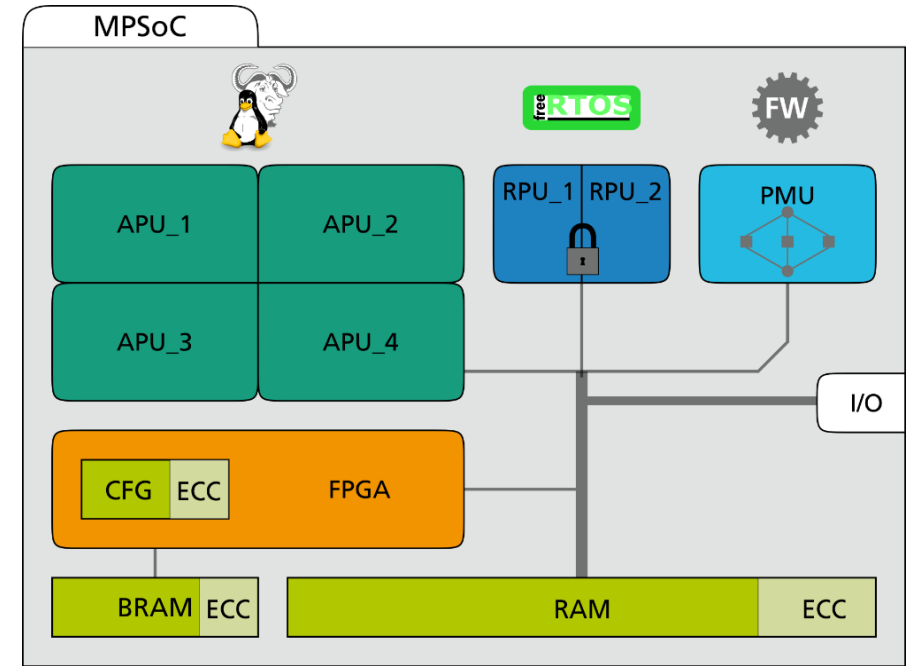
- 2 microSD-Cards (redundant) with SLC flash
- eMMC
- M.2 SSD (SATA or PCIe/NVMe) with SLC flash



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System-on-Module

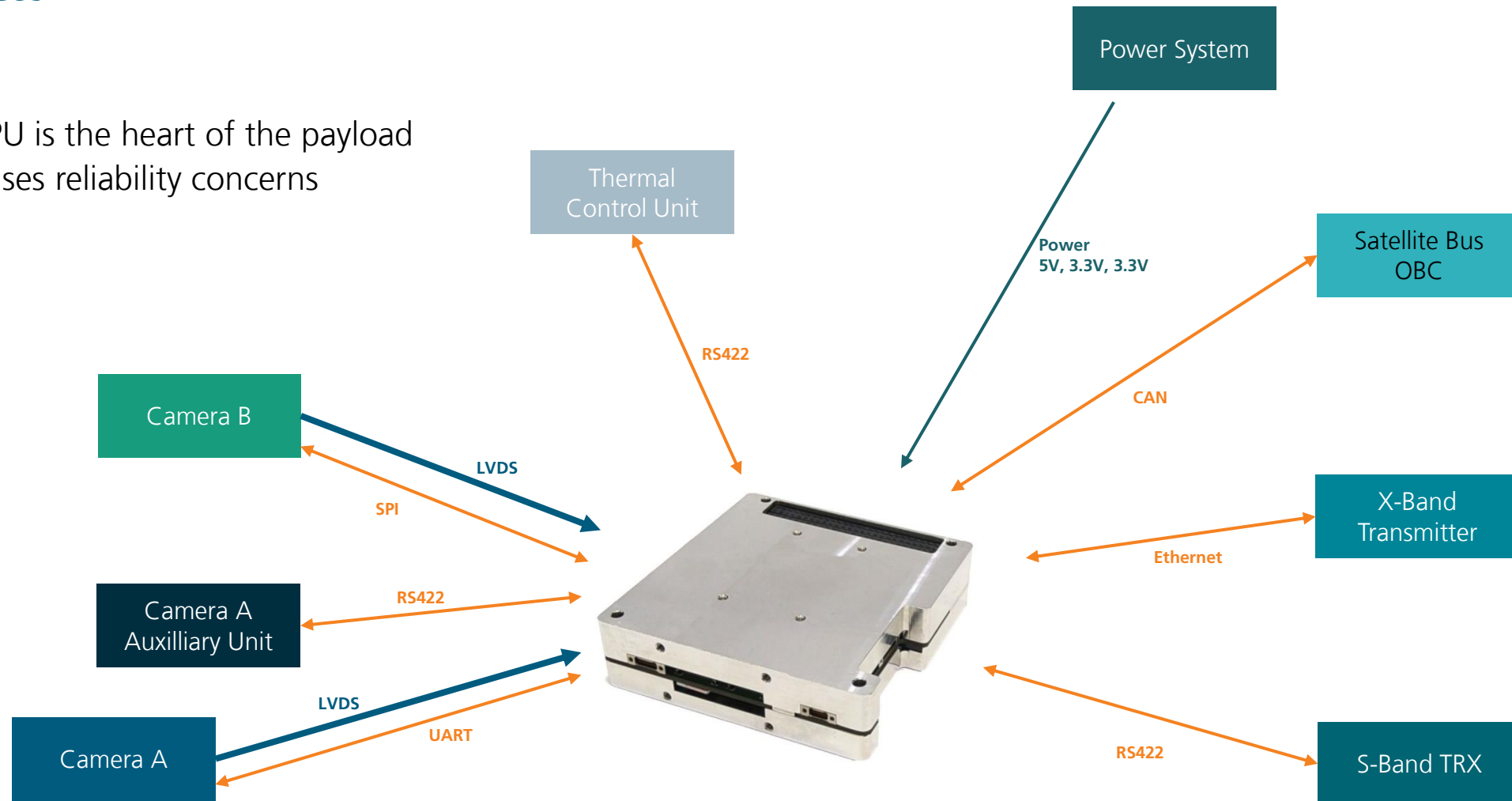
- FPGA-SoC (Xilinx UltraScale+) on small PCB module (COTS)
- Together with RAM, PHYs, eMMC, QSPI Flash...
- Faster development, reduces cost
- Change of SoC type without PCB redesign



EMI Data Processing Unit

Interfaces

- The DPU is the heart of the payload
- This raises reliability concerns



Redundancy

Concept

Idea

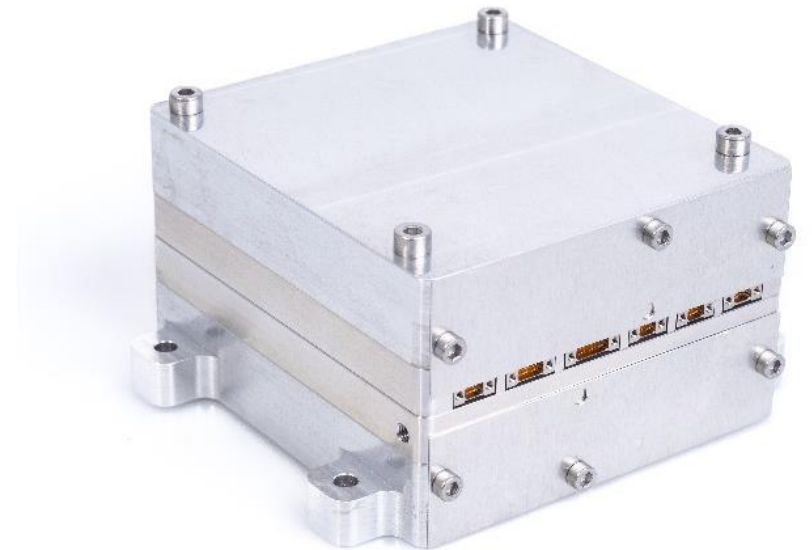
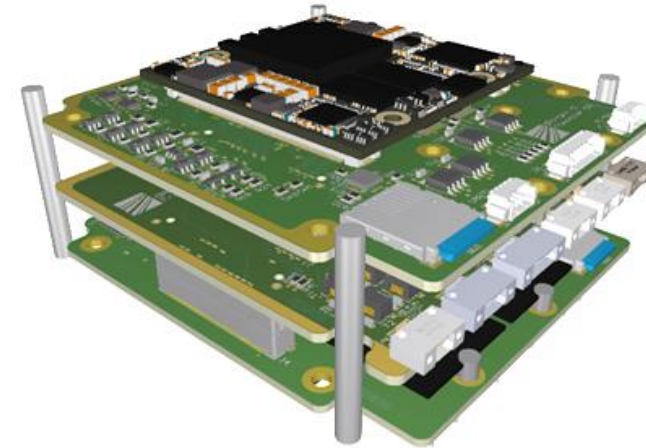
- Duplicate the DPU for increased reliability / life time
- Cold redundant operation, only one DPU module powered at a time
- Late change in the project: keep external interfaces as similar as possible

Solution

- Board level modularity
- Two identical main boards contain as much circuits as possible
- An additional interface board contains only circuits required for interface switching and multiplexing
- The three boards (2x main, 1x interface) are stacked and put in a single housing

Hardware specifications

- Size: 90 x 95 x 56 mm²
- Weight: 820g
- Average Power: 9-12W

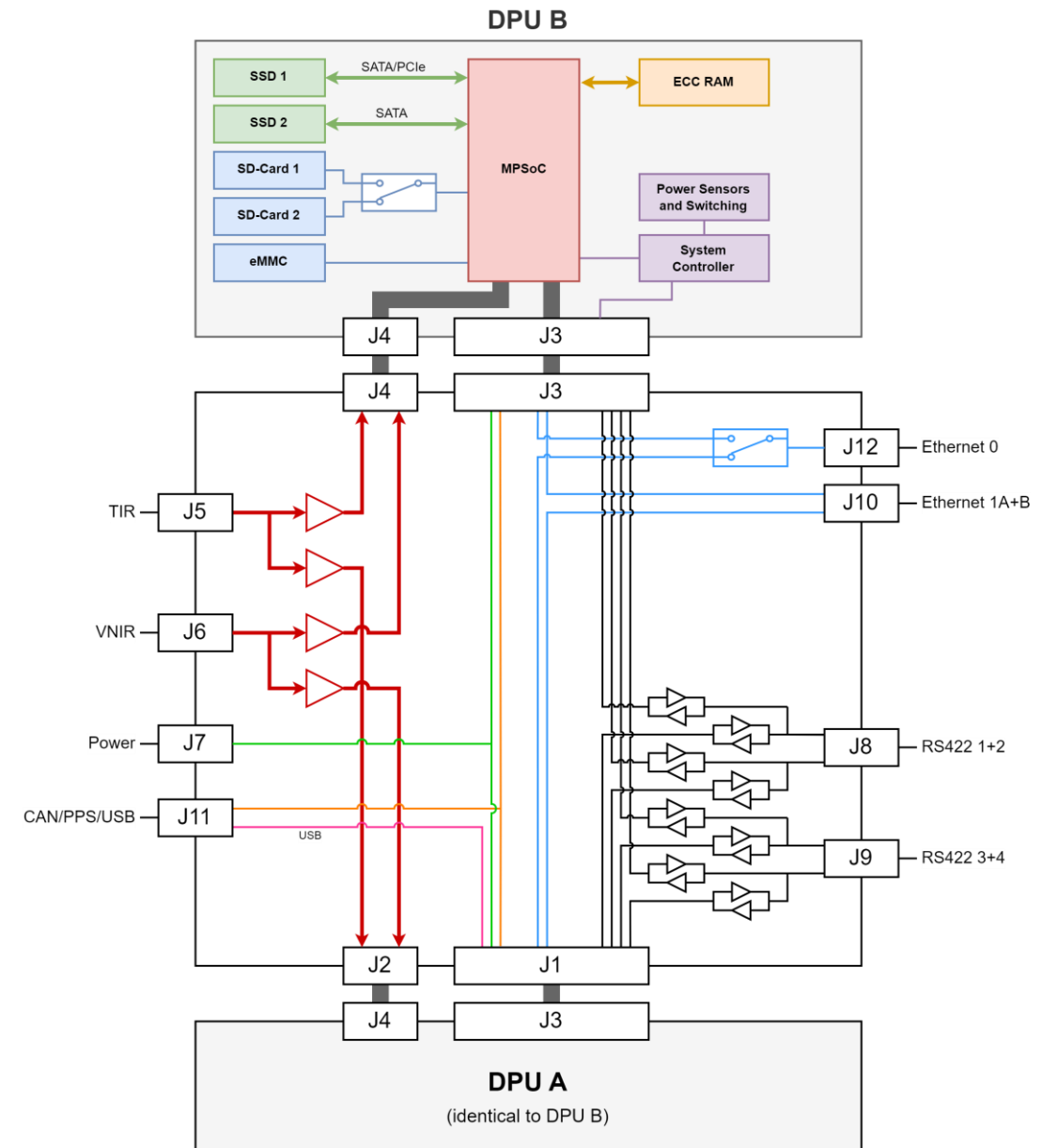


Redundancy

Hardware Configuration

Interfaces

- Power connected in parallel, internal power switching
- CAN connected in parallel
- RS422/485 parallel transceivers
- High-Speed LVDS parallel LVDS buffers
- Ethernet multiplexer



System Controller

- Each DPU module contains a microcontroller called System Controller (SC)
- FRAM-based Texas Instruments MSP430FR5969, a radiation tolerant variant (MSP430FR5969-SP) is available.
- Both SCs are powered on permanently
- Communication to satellite bus and MPSoC via CAN bus
- Functionality
 - Current and voltage monitoring
 - Overcurrent protection
 - Switching of the MPSoC and SSD power supplies

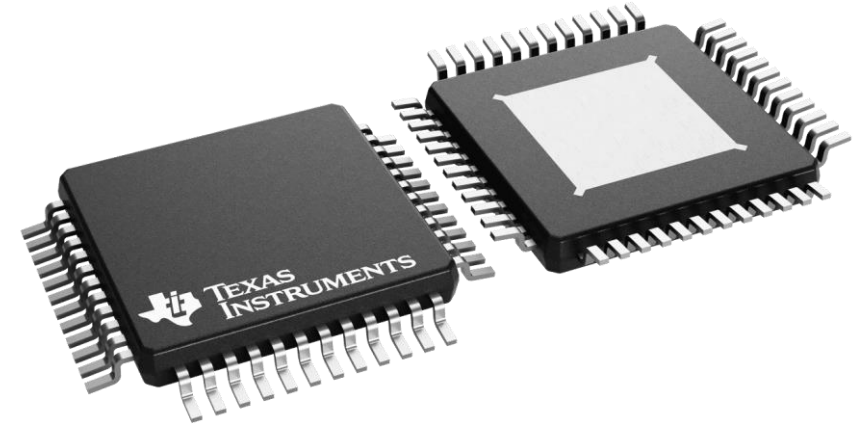
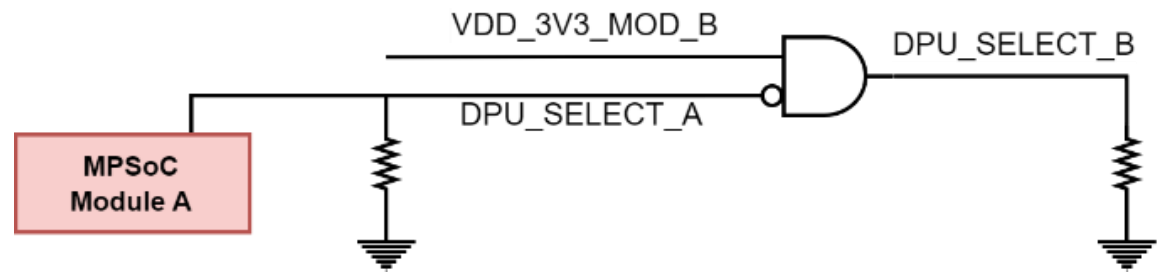


Image: Texas Instruments

Redundancy

Switching

- Basic principle: only one DPU module is powered at a time
- The interfaces are switched automatically by hardware enable signals



DPU_SELECT_A	VDD_3V3_MOD_B	DPU_SELECT_B	Description
0	0	0	Both modules are powered off
1	0	0	A is powered on, B is off
0	1	1	A is off, B is on
1	1	0	Both modules are powered, A is preferred

Interfaces

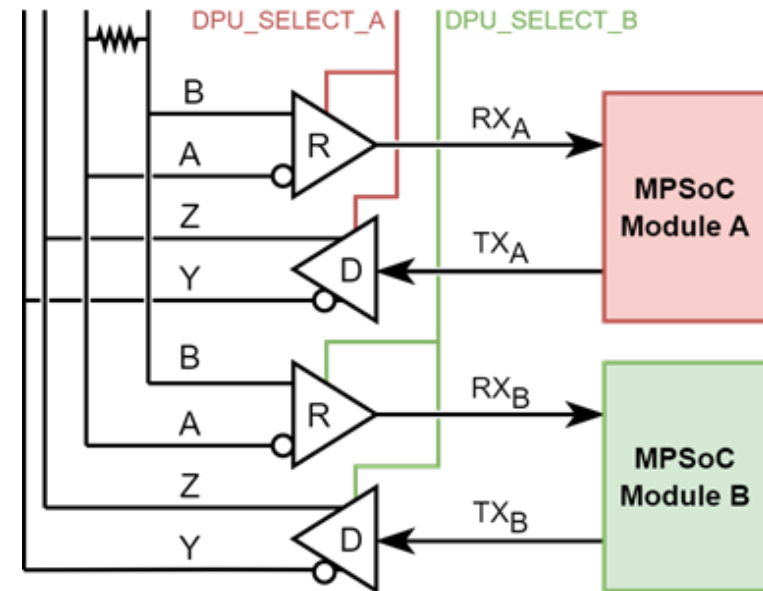
RS422/485 and CAN

RS422

- The DPU has 4 RS422/485 interfaces
- Each DPU module has its own set of transceivers
- The transceivers are enabled and disabled by the respective DPU_SELECT signals
- Disabled transceiver go to a high-impedance state
- Common termination resistors

CAN

- Nothing to do, just connect in parallel



Interfaces

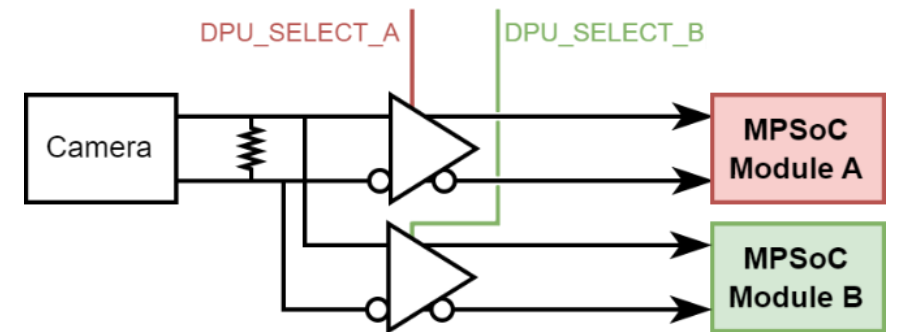
High-Speed LVDS

Challenges

- Requirement: data rates up to 600 Mbit/s
- Signals cannot be connected in parallel to two inputs even if one is in high-impedance configuration. The length of the resulting trace stub length would cause signal integrity problems.
- An LVDS switch would add a single point of failure

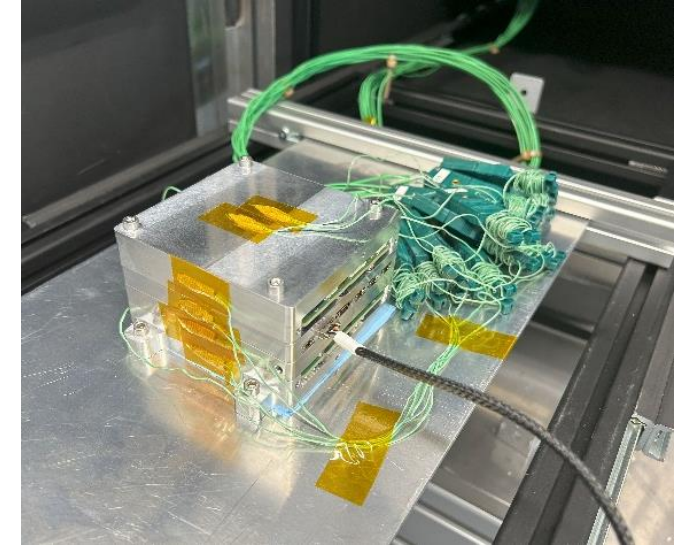
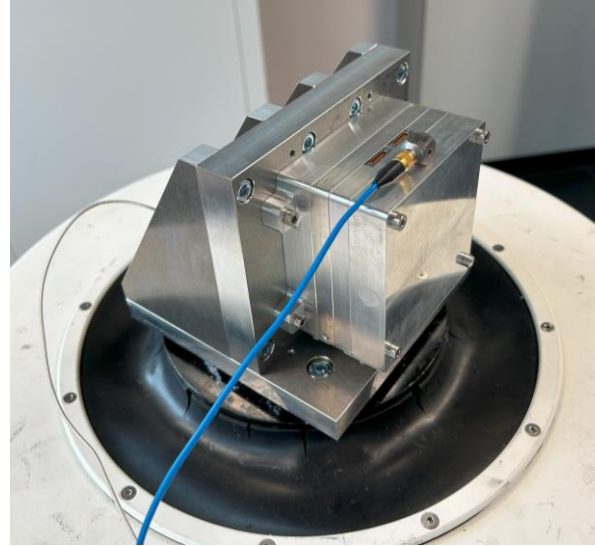
Solution

- Parallel LVDS buffers that share a termination resistor on oppsing sides of the PCB physically very close together.
- Very good results with regards to signal integrity.
- Drawback: additional power consumption



Qualification

- An engineering qualification model (EQM) of the has been partially qualified using the ECSS protoflight approach
- Vibration testing as well as thermal vacuum cycle testing have been passed.
- The DPU supports at least a sustained operating temperature range of -10°C to $+40^{\circ}\text{C}$.
- The random vibration levels are above 13gRMS and the quasi-static loads are above 38g.



Conclusion

- The redundant DPU presented makes use of the inherent advantages of COTS-based systems
 - High data processing performance
 - High storage capacity
 - Miniaturized footprint
 - Moderate power requirements
 - Low parts cost
- The added redundancy increases the expected in-orbit lifetime while keeping the impact on the platform as small as possible.
- The redundant DPU perfectly fits within the volume, mass, and power envelopes of most microsatellite platforms

The redundant DPU is a COTS-based solution for earth observation missions and constellations in the New Space market with requirements beyond CubeSats.

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